DESCRIPTION

Title of Invention

INFRARED SENSOR MODULE

TECHNICAL FIELD

[0001]

The present invention relates to a film-like transparent adhesive and an infrared sensor module.

Priority is claimed on Japanese Patent Application No. 2017-163632, filed on August 28, 2017, the amount of which is incorporated herein by reference.

BACKGROUND ART

[0002]

As a cover member for an infrared sensor such as a human sensor, a cover glass member having high light transmittance in the infrared region has been proposed (Patent Document 1). In an infrared sensor, a cover glass member is provided with a concave portion and is fixed to a frame portion of the infrared sensor as in, for example, Patent Document 2.

Citation List

Patent Literature

[0003]

[Patent Document 1] Japanese Unexamined Patent Application, First Publication No. 2016-040220

CLAIMS

What is claimed is:

1. An infrared sensor module that is formed by bonding an infrared light receiving element having an infrared light receiving portion and a glass wafer by curing using a thermosetting film-like transparent adhesive,

wherein the infrared light receiving portion is provided to receive infrared light that has passed through the glass wafer and the film-like transparent adhesive after curing,

wherein the thermosetting film-like transparent adhesive contains an acrylic resin, an epoxy resin (b1) and a thermosetting agent (b2),

wherein the light transmittance of the thermosetting film-like transparent adhesive after curing at a wavelength of 800 to 2000 nm is all 80% or more.

2. The infrared sensor module adhesive according to claim 1,

wherein the light transmittance of the thermosetting film-like transparent adhesive after curing at a wavelength of 850 nm is 90% or more.

3. The infrared sensor module adhesive according to claim 1 or 2 comprising:

wherein the thermosetting film-like transparent adhesive contains a filler,

wherein the filler has an average particle diameter of 450 nm or less.